



- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## Product Summary



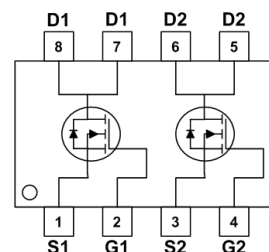
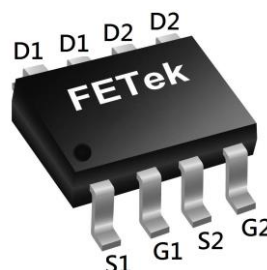
| BVDSS | RDSON | ID |
|-------|-------|----|
| 40V   | 20mΩ  | 8A |

## Description

The FKS4214 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The FKS4214 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

## SOP8 Pin Configuration



## Absolute Maximum Ratings

| Symbol                     | Parameter                                  | Rating     | Units            |
|----------------------------|--------------------------------------------|------------|------------------|
| $V_{DS}$                   | Drain-Source Voltage                       | 40         | V                |
| $V_{GS}$                   | Gate-Source Voltage                        | $\pm 20$   | V                |
| $I_D@T_A=25^\circ\text{C}$ | Continuous Drain Current <sup>1</sup>      | 8          | A                |
| $I_D@T_A=70^\circ\text{C}$ | Continuous Drain Current <sup>1</sup>      | 6          | A                |
| $I_{DM}$                   | Pulsed Drain Current <sup>2</sup>          | 36         | A                |
| EAS                        | Single Pulse Avalanche Energy <sup>3</sup> | 31         | mJ               |
| $I_{AS}$                   | Avalanche Current                          | 25         | A                |
| $P_D@T_A=25^\circ\text{C}$ | Total Power Dissipation <sup>4</sup>       | 1.9        | W                |
| $T_{STG}$                  | Storage Temperature Range                  | -55 to 150 | $^\circ\text{C}$ |
| $T_J$                      | Operating Junction Temperature Range       | -55 to 150 | $^\circ\text{C}$ |

## Thermal Data

| Symbol          | Parameter                                                       | Typ. | Max. | Unit               |
|-----------------|-----------------------------------------------------------------|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient <sup>1</sup> (t $\leq$ 10s) | ---  | 40   | $^\circ\text{C/W}$ |
|                 | Thermal Resistance Junction-ambient <sup>1</sup>                | ---  | 65   | $^\circ\text{C/W}$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

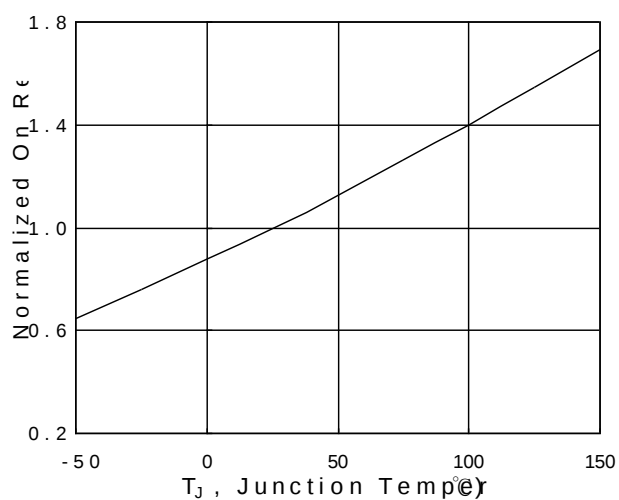
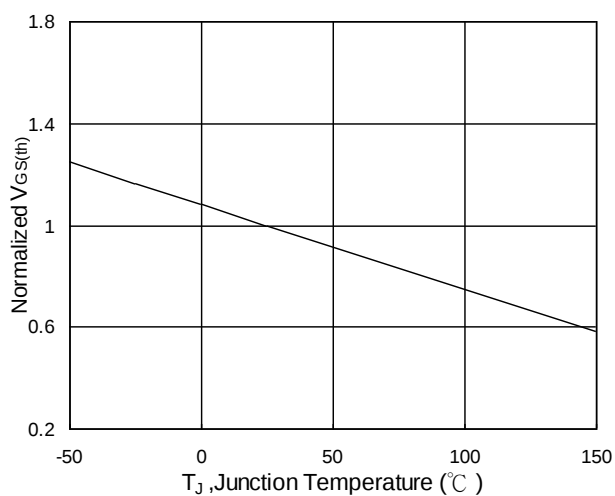
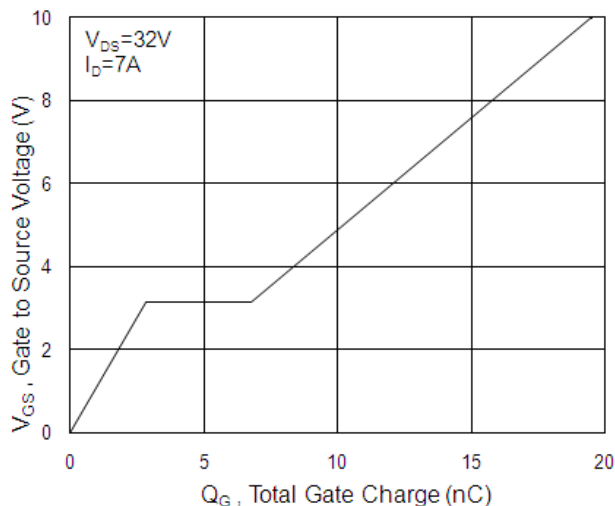
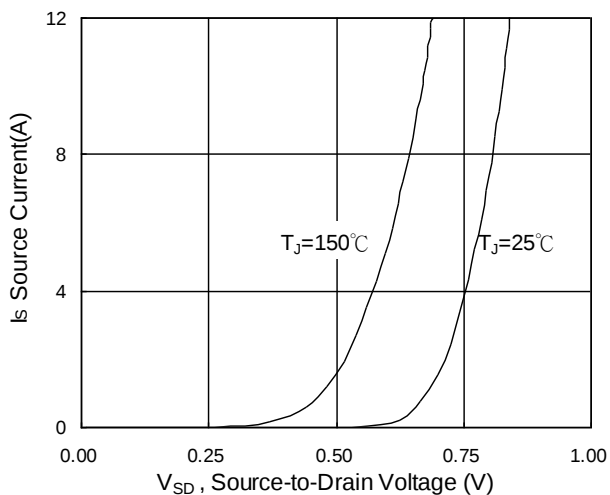
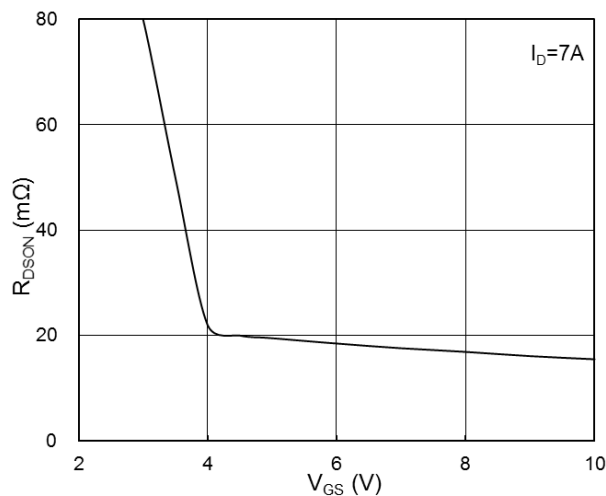
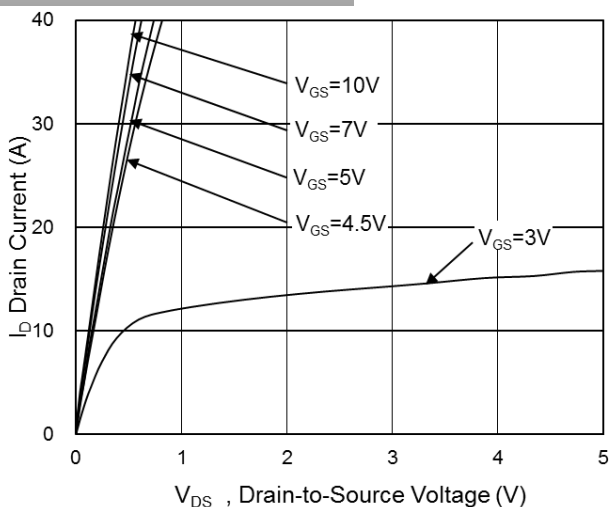
| Symbol                       | Parameter                                      | Conditions                                                | Min. | Typ.  | Max.      | Unit                |
|------------------------------|------------------------------------------------|-----------------------------------------------------------|------|-------|-----------|---------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V$ , $I_D=250\mu A$                              | 40   | ---   | ---       | V                   |
| $\Delta BV_{DSS}/\Delta T_J$ | $BV_{DSS}$ Temperature Coefficient             | Reference to $25^\circ\text{C}$ , $I_D=1mA$               | ---  | 0.032 | ---       | $V/^\circ\text{C}$  |
| $R_{DS(on)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V$ , $I_D=7A$                                   | ---  | 16    | 20        | $m\Omega$           |
|                              |                                                | $V_{GS}=4.5V$ , $I_D=6A$                                  | ---  | 20    | 26        |                     |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}$ , $I_D=250\mu A$                          | 1.2  | 1.6   | 2.5       | V                   |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |                                                           | ---  | -4.8  | ---       | $mV/^\circ\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=32V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$       | ---  | ---   | 1         | $\mu A$             |
|                              |                                                | $V_{DS}=32V$ , $V_{GS}=0V$ , $T_J=55^\circ\text{C}$       | ---  | ---   | 5         |                     |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V$ , $V_{DS}=0V$                            | ---  | ---   | $\pm 100$ | nA                  |
| $g_{fs}$                     | Forward Transconductance                       | $V_{DS}=5V$ , $I_D=7A$                                    | ---  | 32    | ---       | S                   |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V$ , $V_{GS}=0V$ , $f=1MHz$                      | ---  | 2.1   | ---       | $\Omega$            |
| $Q_g$                        | Total Gate Charge (4.5V)                       | $V_{DS}=32V$ , $V_{GS}=4.5V$ , $I_D=7A$                   | ---  | 9.8   | ---       | nC                  |
| $Q_{gs}$                     | Gate-Source Charge                             |                                                           | ---  | 2.8   | ---       |                     |
| $Q_{gd}$                     | Gate-Drain Charge                              |                                                           | ---  | 3.9   | ---       |                     |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{DD}=20V$ , $V_{GS}=10V$ , $R_G=3.3\Omega$<br>$I_D=7A$ | ---  | 2.8   | ---       | ns                  |
| $T_r$                        | Rise Time                                      |                                                           | ---  | 40.4  | ---       |                     |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |                                                           | ---  | 22.8  | ---       |                     |
| $T_f$                        | Fall Time                                      |                                                           | ---  | 6.4   | ---       |                     |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=15V$ , $V_{GS}=0V$ , $f=1MHz$                     | ---  | 1013  | ---       | pF                  |
| $C_{oss}$                    | Output Capacitance                             |                                                           | ---  | 107   | ---       |                     |
| $C_{rss}$                    | Reverse Transfer Capacitance                   |                                                           | ---  | 76    | ---       |                     |

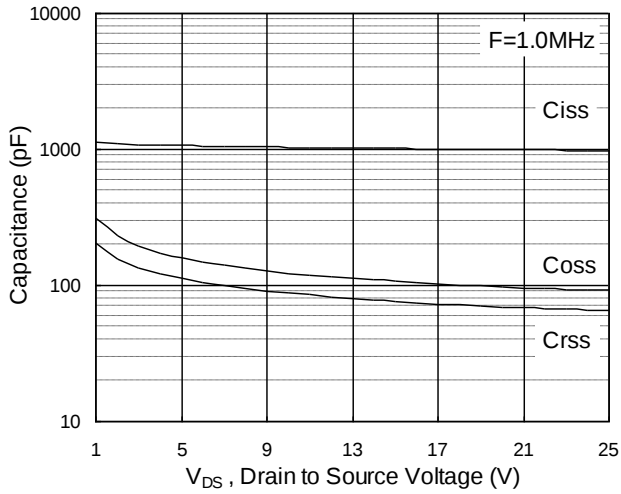
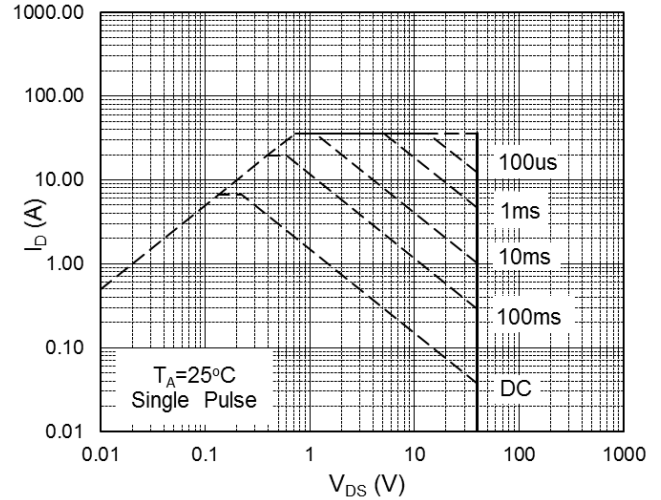
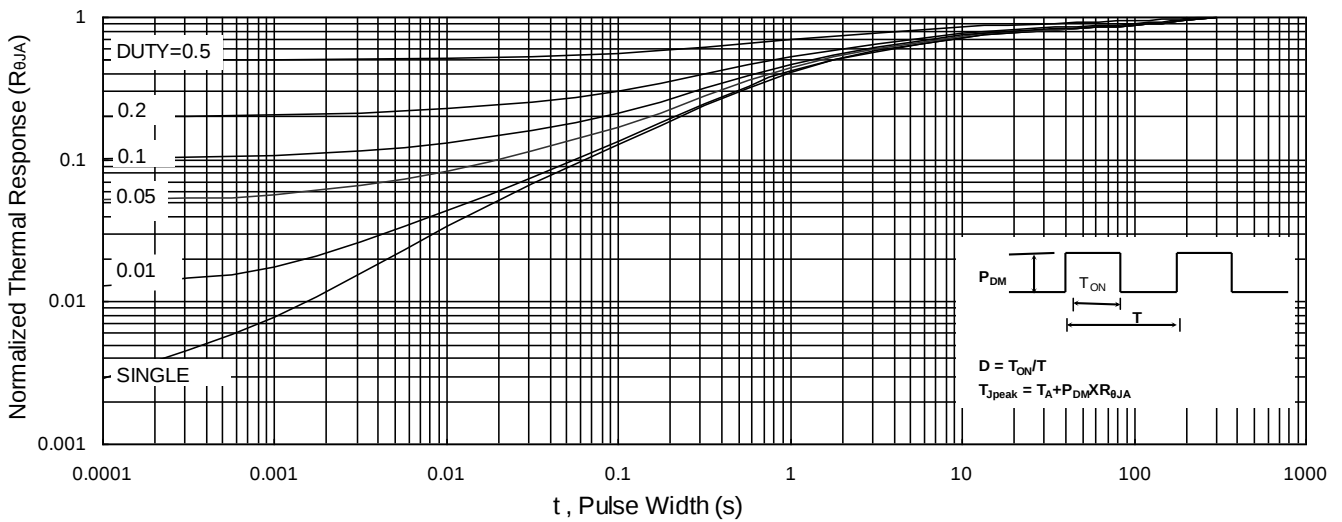
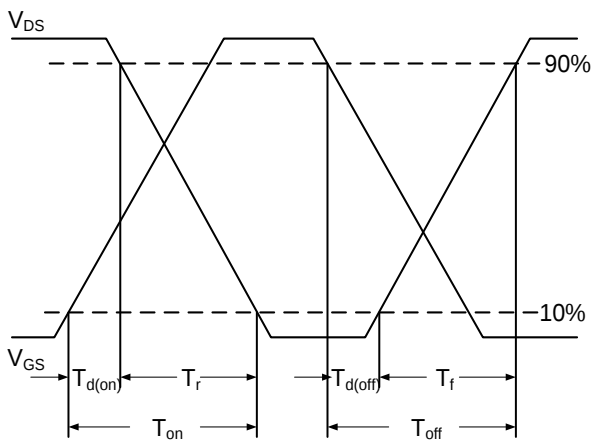
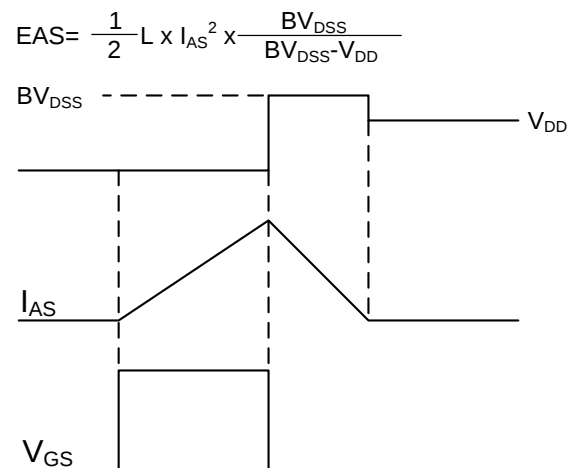
**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                                                | Min. | Typ. | Max. | Unit |
|----------|------------------------------------------|-----------------------------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,5</sup> | $V_G=V_D=0V$ , Force Current                              | ---  | ---  | 8    | A    |
| $I_{SM}$ | Pulsed Source Current <sup>2,5</sup>     |                                                           | ---  | ---  | 36   | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ\text{C}$           | ---  | ---  | 1    | V    |
| $t_{rr}$ | Reverse Recovery Time                    | $I_F=7A$ , $dI/dt=100A/\mu s$ ,<br>$T_J=25^\circ\text{C}$ | ---  | 10   | ---  | nS   |
| $Q_{rr}$ | Reverse Recovery Charge                  |                                                           | ---  | 3.3  | ---  | nC   |

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V$ ,  $V_{GS}=10V$ ,  $L=0.1mH$ ,  $I_{AS}=25A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**Typical Characteristics**



**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**